



## VOIDLESS HERMETICALLY SEALED FAST RECOVERY GLASS RECTIFIERS

Qualified per MIL-PRF-19500/411

*Qualified Levels:  
JAN, JANTX, JANTXV  
and JANS*

### DESCRIPTION

This “fast recovery” rectifier diode series is military qualified and is ideal for high-reliability applications where a failure cannot be tolerated. These industry-recognized 3.0 amp rated rectifiers for working peak reverse voltages from 50 to 600 volts are hermetically sealed with voidless-glass construction using an internal “Category 1” metallurgical bond. These devices are also available in surface mount MELF package configurations. Microsemi also offers numerous other rectifier products to meet higher and lower current ratings with various recovery time speed requirements including fast and ultrafast device types in both through-hole and surface mount packages.

**Important:** For the latest information, visit our website <http://www.microsemi.com>.

### FEATURES

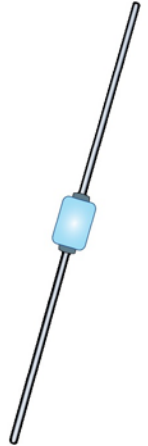
- Popular JEDEC registered 1N5415 thru 1N5420 series.
- Voidless hermetically sealed glass package.
- Quadruple-layer passivation.
- Internal “Category 1” metallurgical bonds.
- Working Peak Reverse Voltage 50 to 600 volts.
- JAN, JANTX, JANTXV and JANS qualifications available per MIL-PRF-19500/411.
- RoHS compliant versions available (commercial grade only).

### APPLICATIONS / BENEFITS

- Fast recovery 3 amp 50 to 600 volt rectifiers.
- Military and other high-reliability applications.
- General rectifier applications including bridges, half-bridges, catch diodes, etc.
- High forward surge current capability.
- Extremely robust construction.
- Low thermal resistance.
- Controlled avalanche with peak reverse power capability.
- Inherently radiation hard as described in Microsemi “[MicroNote 050](#)”.

### MAXIMUM RATINGS


Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T <sub>J</sub> and T <sub>STG</sub>	-65 to +175	°C
Thermal Resistance Junction-to-Lead <sup>(1)</sup>	R <sub>θJL</sub>	22	°C/W
Forward Surge Current @ 8.3 ms half-sine	I <sub>FSM</sub>	80	A
Average Rectified Forward Current <sup>(4)</sup>	I <sub>O</sub> <sup>(2, 3)</sup>	3	A
		@ T <sub>A</sub> = +55 °C	
°C	I <sub>O</sub> <sup>(3)</sup>	2	
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	V
		1N5415	
		1N5416	
		1N5417	
		1N5418	
		1N5419	
1N5420	600		
Maximum Reverse Recovery Time <sup>(5)</sup>	t <sub>rr</sub>	150	ns
		1N5415	
		1N5416	
		1N5417	
		1N5418	
		1N5419	
1N5420	400		
Solder Temperature @ 10 s	T <sub>SP</sub>	260	°C



**“B” Package**

Also available in:

**“B” SQ-MELF  
(D-5B) Package**  
(surface mount)

 [1N5415US – 1N5420US](#)

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[www.microsemi.com](http://www.microsemi.com)

See notes on next page.

**MAXIMUM RATINGS**

- Notes:**
1. At 3/8 inch (10 mm) lead length from body.
  2. Derate linearly at 22 mA/°C for 55 °C ≤ T<sub>A</sub> ≤ 100 °C.
  3. Above T<sub>A</sub> = 100 °C, derate linearly at 26.7 mA/°C to zero at T<sub>A</sub> = 175 °C.
  4. These ambient ratings are for PC boards where thermal resistance from mounting point to ambient is sufficiently controlled where T<sub>J(max)</sub> does not exceed 175 °C.
  5. I<sub>F</sub> = 0.5 A, I<sub>RM</sub> = 1 A, I<sub>R(REC)</sub> = 0.250 A.

**MECHANICAL and PACKAGING**

- CASE: Hermetically sealed voidless hard glass with tungsten slugs.
- TERMINALS: Axial-leads are tin/lead (Sn/Pb) over copper. RoHS compliant matte-tin is available for commercial grade only.
- MARKING: Body paint and part number.
- POLARITY: Cathode band.
- TAPE & REEL option: Standard per EIA-296. Contact factory for quantities.
- WEIGHT: 750 milligrams.
- See [Package Dimensions](#) on last page.

**PART NOMENCLATURE**

**JAN 1N5415 (e3)**

**Reliability Level**

JAN = JAN Level  
 JANTX = JANTX Level  
 JANTXV = JANTXV Level  
 JANS = JANS Level  
 Blank = commercial

**JEDEC type number**

See [Electrical Characteristics](#) table

**RoHS Compliance**

e3 = RoHS compliant ([available on commercial grade only](#))  
 Blank = non-RoHS compliant

**SYMBOLS & DEFINITIONS**

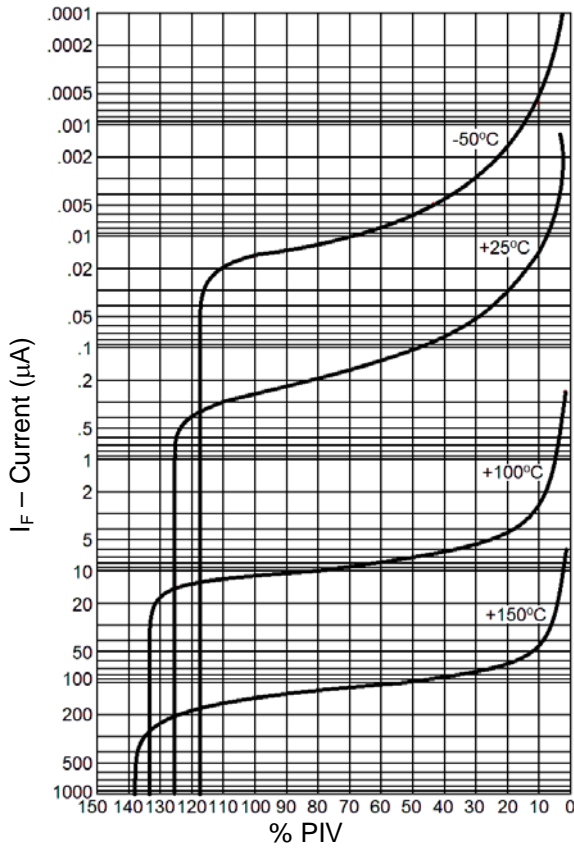
Symbol	Definition
V <sub>BR</sub>	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.
V <sub>RWM</sub>	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range excluding all transient voltages (ref JESD282-B).
I <sub>O</sub>	Average Rectified Output Current: The Output Current averaged over a full cycle with a 50 Hz or 60 Hz sine-wave input and a 180 degree conduction angle.
V <sub>F</sub>	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.
I <sub>R</sub>	Maximum Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
t <sub>rr</sub>	Reverse Recovery Time: The time interval between the instant the current passes through zero when changing from the forward direction to the reverse direction and a specified decay point after a peak reverse current occurs.

**ELECTRICAL CHARACTERISTICS**

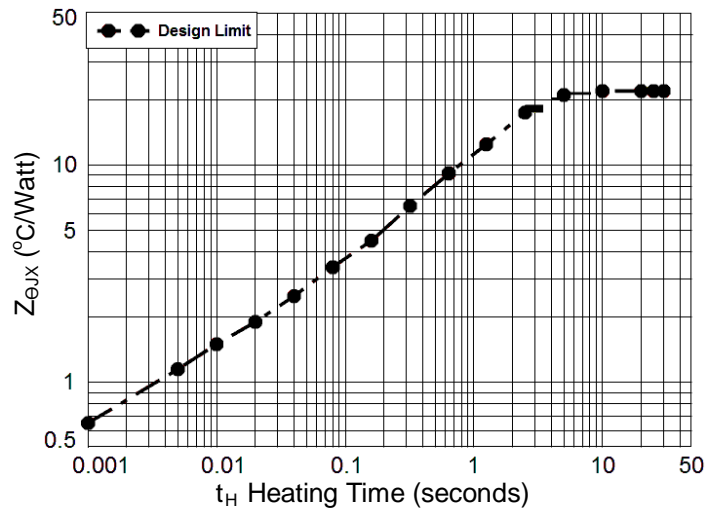
TYPE	MINIMUM BREAKDOWN VOLTAGE  $V_{BR} @ 50 \mu A$	FORWARD VOLTAGE  $V_F @ 9 A$		MAXIMUM REVERSE CURRENT $I_R @ V_{RWM}$		CAPACITANCE C  $V_R @ 4 V$  pF
		MIN. Volts	MAX. Volts	25 °C $\mu A$	100 °C $\mu A$	
	Volts					
1N5415	55	0.6	1.5	1.0	20	550
1N5416	110	0.6	1.5	1.0	20	430
1N5417	220	0.6	1.5	1.0	20	250
1N5418	440	0.6	1.5	1.0	20	165
1N5419	550	0.6	1.5	1.0	20	140
1N5420	660	0.6	1.5	1.0	20	120

**NOTE 1:**  $I_F = 0.5 A$ ,  $I_{RM} = 1 A$ ,  $I_{R(REC)} = 0.250 A$ .

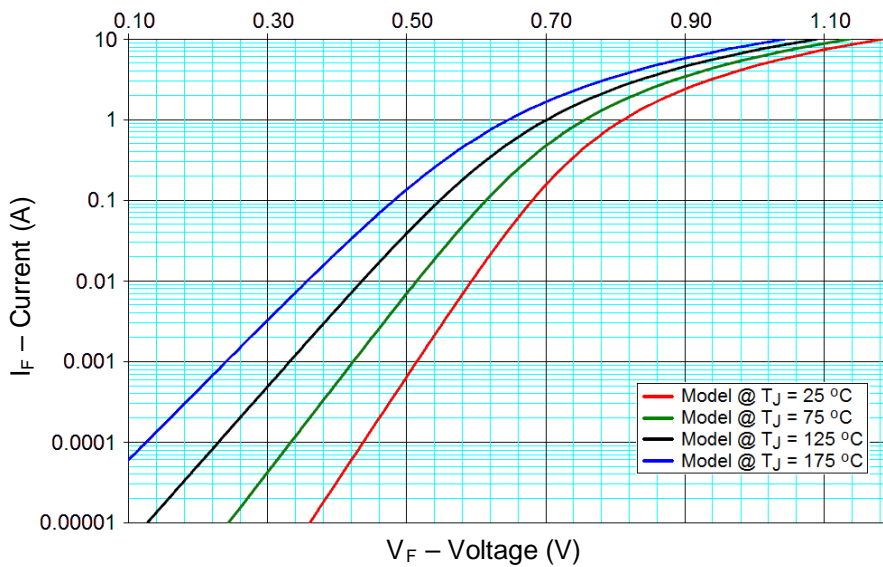
GRAPHS



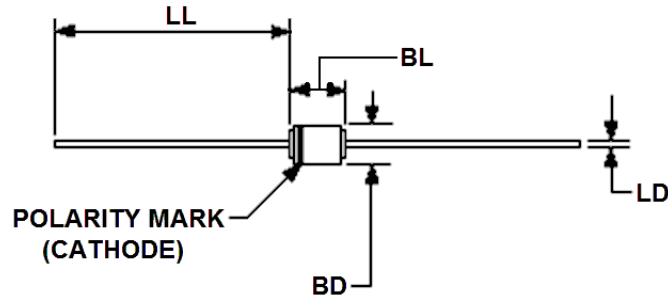
**FIGURE 1**  
Typical Reverse Current vs. PIV



**FIGURE 2**  
Maximum Thermal Impedance



**FIGURE 3**  
Typical Forward Current vs. Forward Voltage

**PACKAGE DIMENSIONS**


Symbol	Dimensions				Notes
	Inch		Millimeters		
	Min	Max	Min	Max	
<b>BD</b>	0.110	0.180	2.79	4.57	3
<b>LD</b>	0.036	0.042	0.91	1.07	4
<b>BL</b>	0.130	0.260	3.30	6.60	4
<b>LL</b>	0.90	1.30	22.9	33.0	

**NOTES:**

1. Dimensions are in inches.
2. Millimeter equivalents are given for general information only.
3. Dimension BD shall be measured at the largest diameter.
4. The BL dimension shall include the entire body including slugs and sections of the lead over which the diameter is uncontrolled. This uncontrolled area is defined as the zone between the edge of the diode body and extending .050 inch (1.27 mm) onto the leads.
5. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi$ x symbology.

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